



**ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® TSSOP-16**

<b>Stress</b>	<b>Sample Size</b>	<b>Device Hr./Cyc</b>	<b>Condition</b>	<b>Total Fails</b>	<b>Fail Percentage</b>
HAST	154	15,400	130°C, 85%RH	0	0.00
Pressure Pot	165	15,840	121°, 15 PSIG	0	0.00
Solderability	20	N/A	883 M2003	0	0.00
Temp Cycle	163	81,500	-65°C-150°C	0	0.00